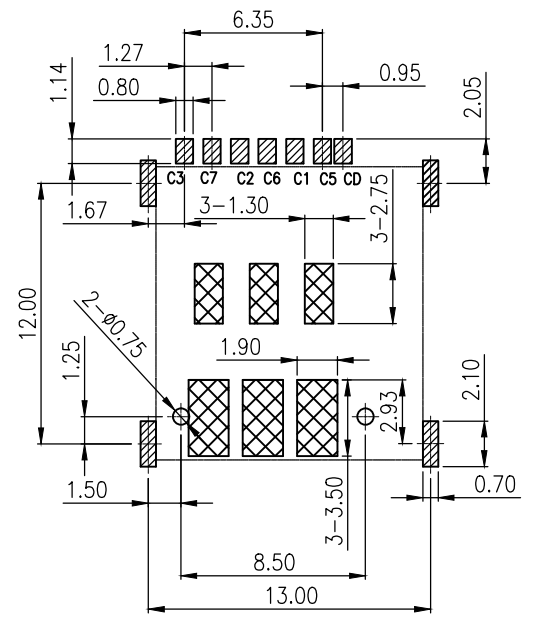
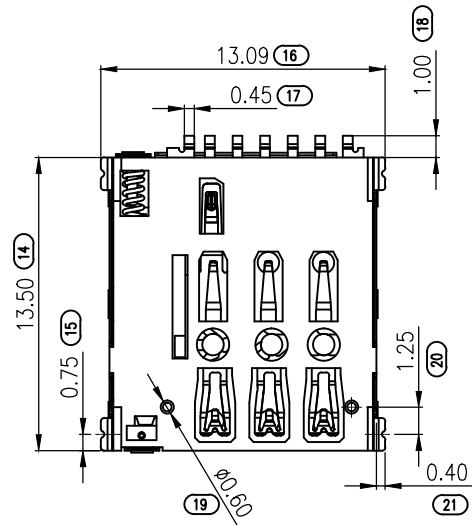
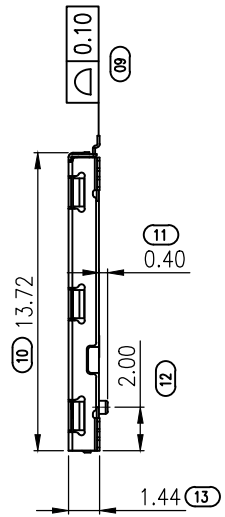
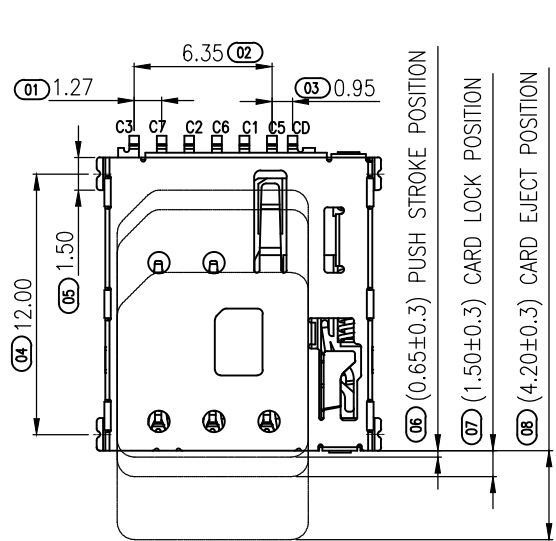
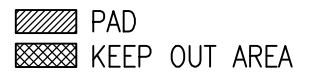


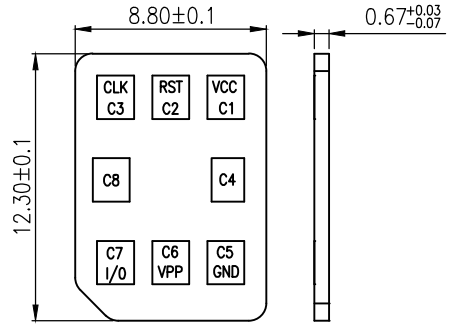
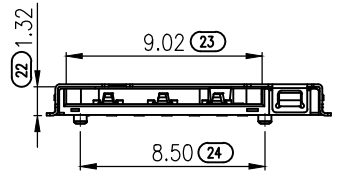
REV.	ECN.NO.	MODIFY.CONTENT	DATE
A0		NEW	2021/07/20



RECOMMENDED PCB LAYOUT  
GENERAL TOLERANCE ±0.05

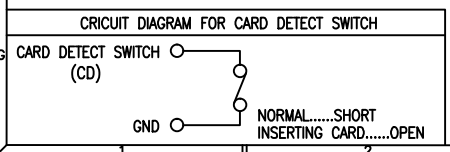


- NOTES:
- MATERIAL:  
HOUSING:HI-TEMP. PLASIC UL 94V-0  
CONTACT: COPPER ALLOY  
SHELL: STAINLESS STEEL
  - PLATING :  
TERMINAL:  
CONTACT AREA: Au GOLD FLASH.  
SOLDER AREA: AU GOLD FLASH.  
UNDER PLATE: NICKEL.  
SHELL: NICKEL PLATED OVER ALL.  
SOLDER AREA: GOLD FLASH.
  - SPECIALITY:  
3.1 Rated current:1.0A  
3.2 Rated voltage:30V  
3.3 Contact Resistance:50mΩ MAX  
3.4 Insulation Resistance:1000MΩ MIN 500V DC  
3.5 Dielectric withstanding voltage: 500V AC.  
3.6 Solder ability:260+0/-5°C, 30±10s.  
3.7 Durability:5000 Cycles Min.  
3.8 Operating condition:Temperature-40°C~+85°C;  
Humidity 80% R.H MAX



NANO SIM CARD

SIM pin Assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O



GENERAL TOLERANCE		DWG NO.	APPD:	WIND	Scale	1:1
X.±0.45	x.±5°	Title	CHKD:		UNIT	mm
.X±0.35	.x'±2°		DR:		视角	
.XX±0.25	.xx'±1°	Part NO.	Date	2021/07/20	版本	A2
.XXX±0.15	.xxx'±0.5°	深圳市文章济美科技有限公司				
SHEET						